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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lce623t-04i-ss

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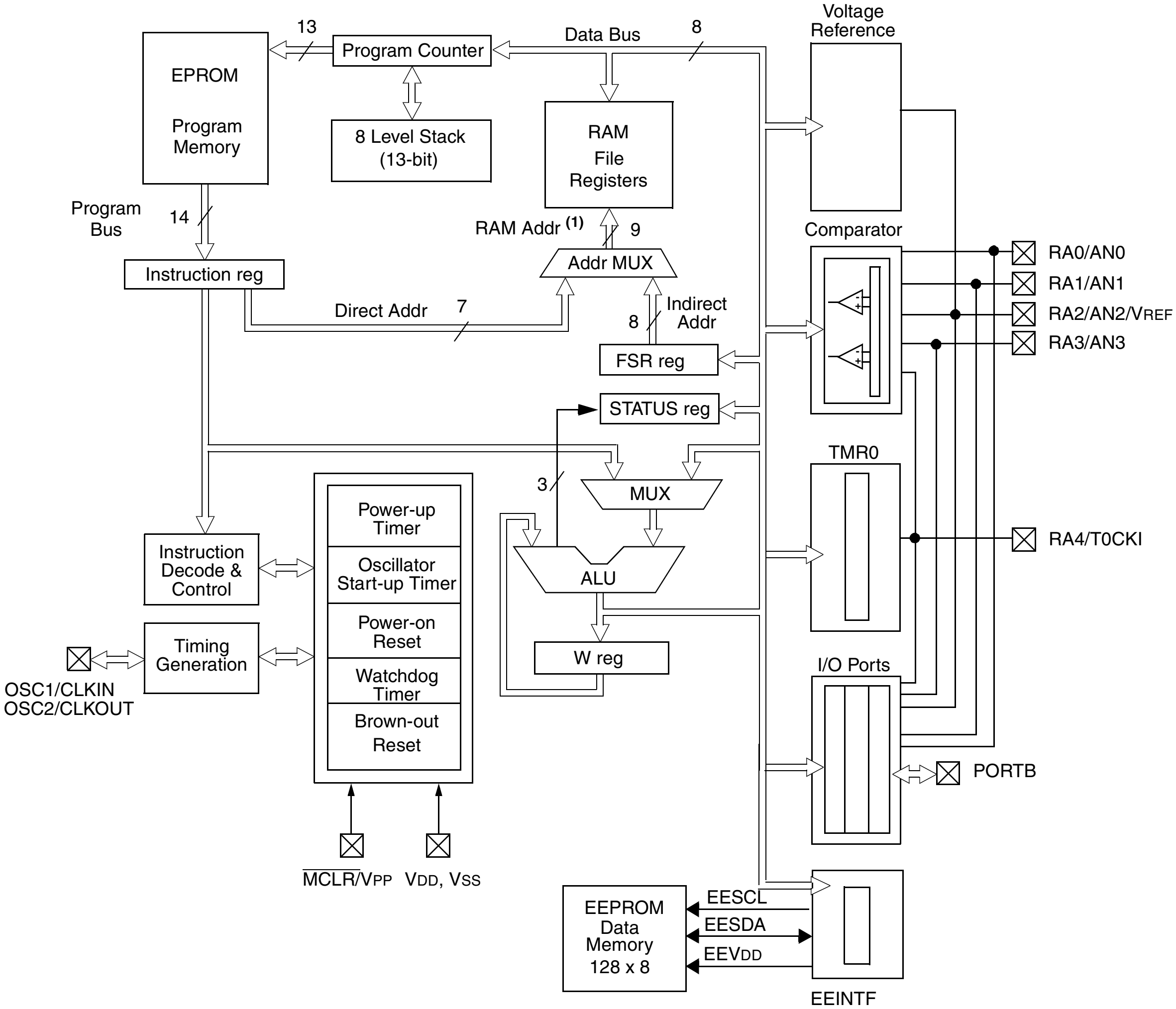
We appreciate your assistance in making this a better document.

FIGURE 3-1: BLOCK DIAGRAM

Device	Program Memory	Data Memory (RAM)	EEPROM DATA MEMORY
PIC16CE623	512 x 14	96 x 8	128 x 8
PIC16CE624	1K x 14	96 x 8	128 x 8
PIC16CE625	2K x 14	128 x 8	128 x 8



Note 1: Higher order bits are from the STATUS register.

4.2.2.2 OPTION REGISTER

The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the external RB0/INT interrupt, TMR0 and the weak pull-ups on PORTB.

Note:	To achieve a 1:1 prescaler assignment for TMR0, assign the prescaler to the WDT (PSA = 1).

REGISTER 4-2: OPTION REGISTER (ADDRESS 81H)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
-n = Value at POR reset
-x = Unknown at POR reset

bit 7: **$\overline{\text{RBPU}}$**: PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6: **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5: **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4: **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3: **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0: **PS<2:0>**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

5.2 PORTB and TRISB Registers

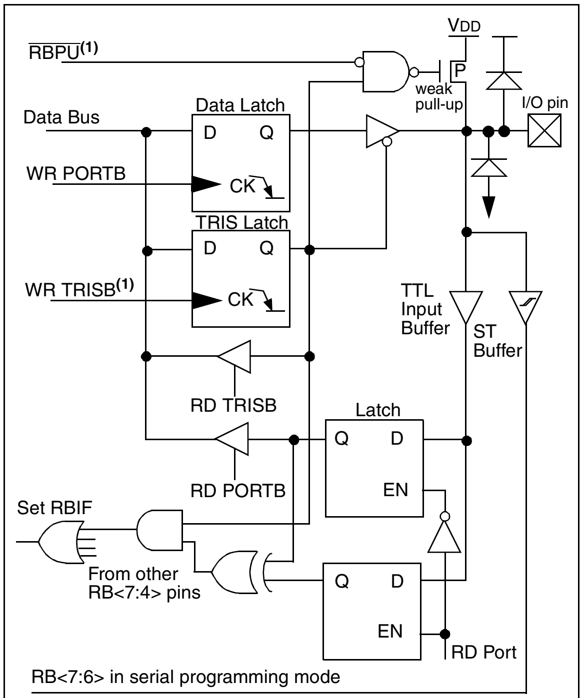
PORTB is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISB. A '1' in the TRISB register puts the corresponding output driver in a high impedance mode. A '0' in the TRISB register puts the contents of the output latch on the selected pin(s).

Reading PORTB register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

Each of the PORTB pins has a weak internal pull-up ($\approx$200 μA typical). A single control bit can turn on all the pull-ups. This is done by clearing the $\overline{\text{RBPU}}$ (OPTION<7>) bit. The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on Power-on Reset.

Four of PORTB's pins, RB<7:4>, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB<7:4> pin configured as an output is excluded from the interrupt on change comparison). The input pins of RB<7:4> are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB<7:4> are OR'ed together to generate the RBIF interrupt (flag latched in INTCON<0>).

FIGURE 5-5: BLOCK DIAGRAM OF RB<7:4> PINS



Note 1: TRISB = 1 enables weak pull-up if $\overline{\text{RBPU}}$ = '0' (OPTION<7>).

This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB. This will end the mismatch condition.
b) Clear flag bit RBIF.

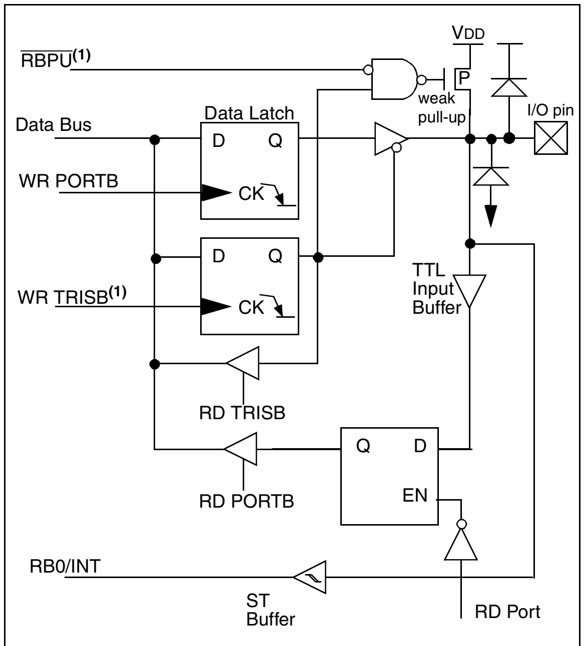
A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a key pad and make it possible for wake-up on key-depression. (See AN552, "Implementing Wake-Up on Key Strokes".)

> **Note:** If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.

FIGURE 5-6: BLOCK DIAGRAM OF RB<3:0> PINS



Note 1: TRISB = 1 enables weak pull-up if $\overline{\text{RBPU}}$ = '0' (OPTION<7>).

5.3 I/O Programming Considerations

5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The `BCF` and `BSF` instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a `BSF` operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the `BSF` operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bidirectional I/O pin (i.e., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and re-written to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched into output mode later on, the content of the data latch may now be unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read modify write instructions (i.e., `BCF, BSF`, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-2 shows the effect of two sequential read-modify-write instructions (i.e., `BCF, BSF`, etc.) on an I/O port.

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

EXAMPLE 5-2: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

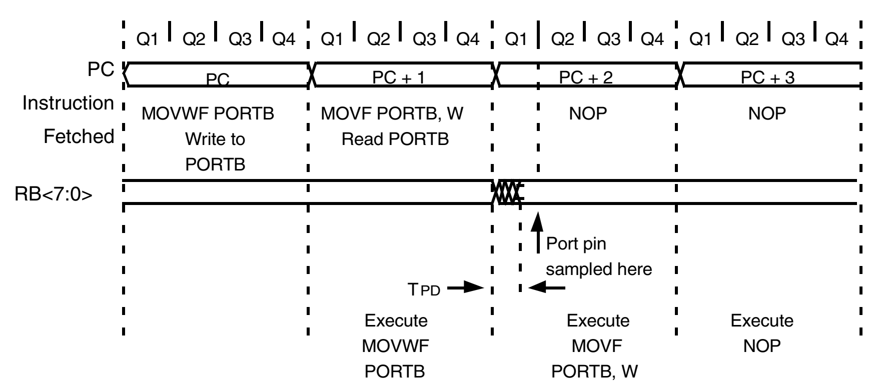
```
; Initial PORT settings:  PORTB<7:4> Inputs
;
;                         PORTB<3:0> Outputs
; PORTB<7:6> have external pull-up and are not
; connected to other circuitry
;
;                         PORT latch  PORT pins
;                         ----------  ----------

    BCF PORTB, 7          ; 01pp pppp   11pp pppp
    BCF PORTB, 6          ; 10pp pppp   11pp pppp
    BSF STATUS,RP0        ;
    BCF TRISB, 7          ; 10pp pppp   11pp pppp
    BCF TRISB, 6          ; 10pp pppp   10pp pppp
;
; Note that the user may have expected the pin
; values to be 00pp pppp. The 2nd BCF caused
; RB7 to be latched as the pin value (High).
```

5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-7). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction causes that file to be read into the CPU. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with an NOP or another instruction not accessing this I/O port.

FIGURE 5-7: SUCCESSIVE I/O OPERATION



Note:

This example shows write to PORTB followed by a read from PORTB.

Note that:

data setup time = (0.25 T_{CY} - T_{PD}) where T_{CY} = instruction cycle and T_{PD} = propagation delay of Q1 cycle to output valid.

Therefore, at higher clock frequencies, a write followed by a read may be problematic.

FIGURE 6-1: DATA TRANSFER SEQUENCE ON THE SERIAL BUS

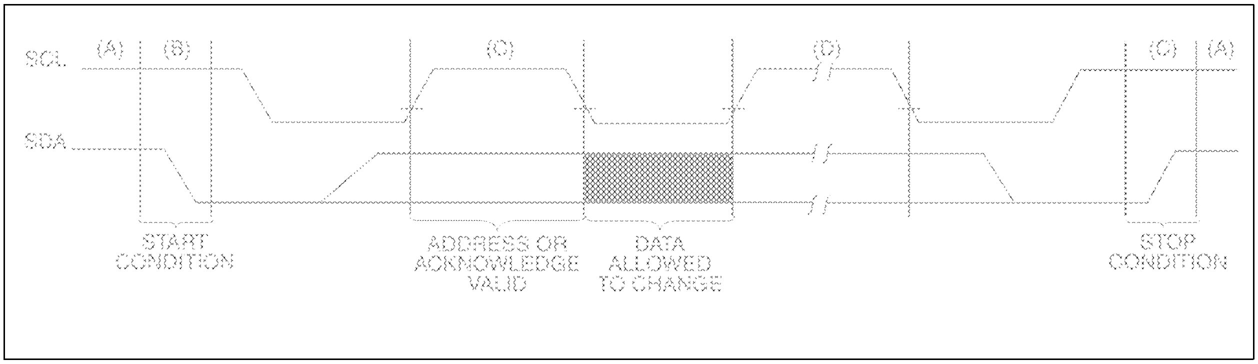
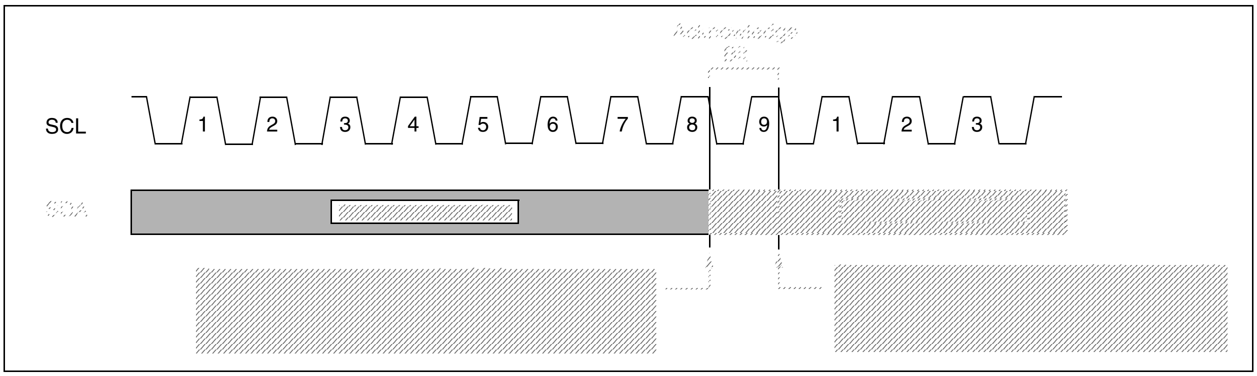


FIGURE 6-2: ACKNOWLEDGE TIMING

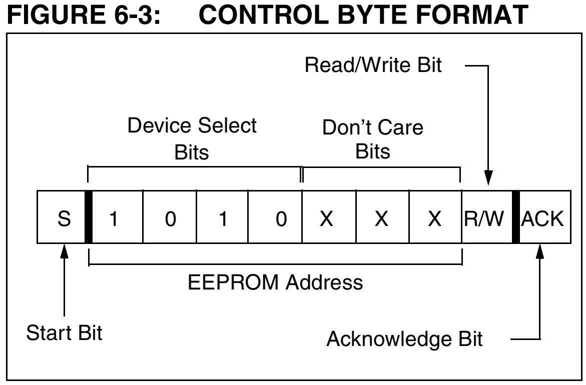


6.2 Device Addressing

After generating a START condition, the processor transmits a control byte consisting of a EEPROM address and a Read/$\overline{\text{Write}}$ bit that indicates what type of operation is to be performed. The EEPROM address consists of a 4-bit device code (1010) followed by three don't care bits.

The last bit of the control byte determines the operation to be performed. When set to a one, a read operation is selected, and when set to a zero, a write operation is selected. (Figure 6-3). The bus is monitored for its corresponding EEPROM address all the time. It generates an acknowledge bit if the EEPROM address was true and it is not in a programming mode.

FIGURE 6-3: CONTROL BYTE FORMAT



7.2 Using Timer0 with External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (TOSC) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

7.2.1 EXTERNAL CLOCK SYNCHRONIZATION

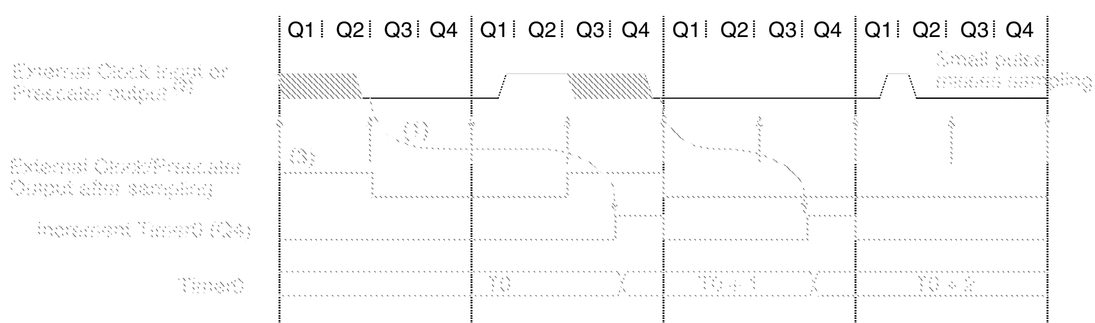
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 7-5). Therefore, it is necessary for T0CKI to be high for at least 2TOSC (and a small RC delay of 20 ns) and low for at least 2TOSC (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple-counter type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple-counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4TOSC (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

7.2.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the TMR0 is actually incremented. Figure 7-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 7-5: TIMER0 TIMING WITH EXTERNAL CLOCK



Note 1: Delay from clock input change to Timer0 increment is 3Tosc to 7Tosc. (Duration of Q = Tosc). Therefore, the error in measuring the interval between two edges on Timer0 input = ±4Tosc max.
2: External clock if no prescaler selected; prescaler output otherwise.
3: The arrows indicate the points in time where sampling occurs.

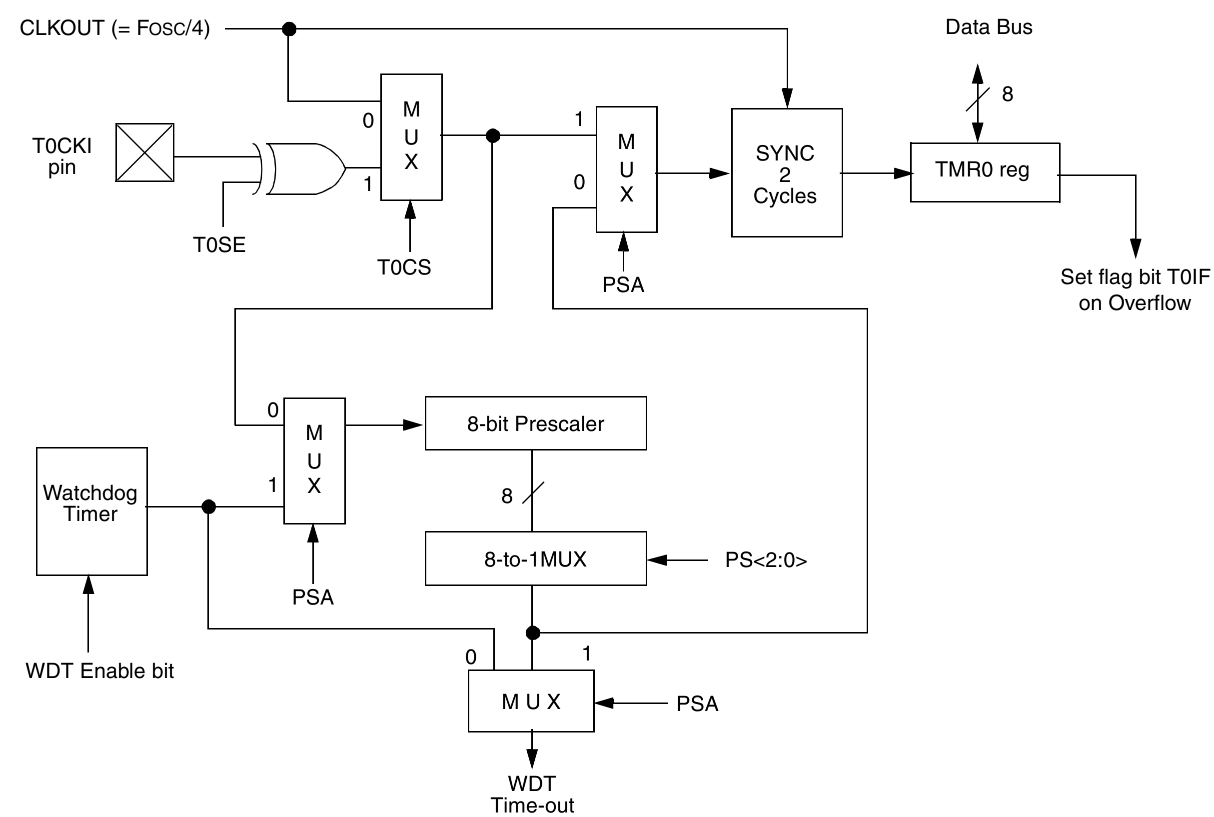
7.3 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer, respectively (Figure 7-6). For simplicity, this counter is being referred to as “prescaler” throughout this data sheet. Note that there is only one prescaler available which is mutually exclusive between the Timer0 module and the Watchdog Timer. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the Watchdog Timer and vice-versa.

The PSA and PS<2:0> bits (OPTION<3:0>) determine the prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (i.e., `CLRF 1`, `MOVWF 1`, `BSF 1,x`....etc.) will clear the prescaler. When assigned to WDT, a `CLRWDT` instruction will clear the prescaler along with the Watchdog Timer. The prescaler is not readable or writable.

FIGURE 7-6: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



Note: T0SE, T0CS, PSA, PS<2:0> are bits in the OPTION register.

NOTES:

9.0 VOLTAGE REFERENCE MODULE

The Voltage Reference is a 16-tap resistor ladder network that provides a selectable voltage reference. The resistor ladder is segmented to provide two ranges of V_{REF} values and has a power-down function to conserve power when the reference is not being used. The VRCON register controls the operation of the reference as shown in Register 9-1. The block diagram is given in Figure 9-1.

9.1 Configuring the Voltage Reference

The Voltage Reference can output 16 distinct voltage levels for each range.

The equations used to calculate the output of the Voltage Reference are as follows:

if $V_{RR} = 1$: $V_{REF} = (V_R\langle 3:0\rangle/24) \times V_{DD}$

if $V_{RR} = 0$: $V_{REF} = (V_{DD} \times 1/4) + (V_R\langle 3:0\rangle/32) \times V_{DD}$

The setting time of the Voltage Reference must be considered when changing the V_{REF} output (Table 13-1). Example 9-1 shows an example of how to configure the Voltage Reference for an output voltage of 1.25V with V_{DD} = 5.0V.

REGISTER 9-1: VRCON REGISTER (ADDRESS 9Fh)

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
VREN	VROE	VRR	—	VR3	VR2	VR1	VR0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset

bit 7: **VREN:** V_{REF} Enable
1 = V_{REF} circuit powered on
0 = V_{REF} circuit powered down, no I_{DD} drain

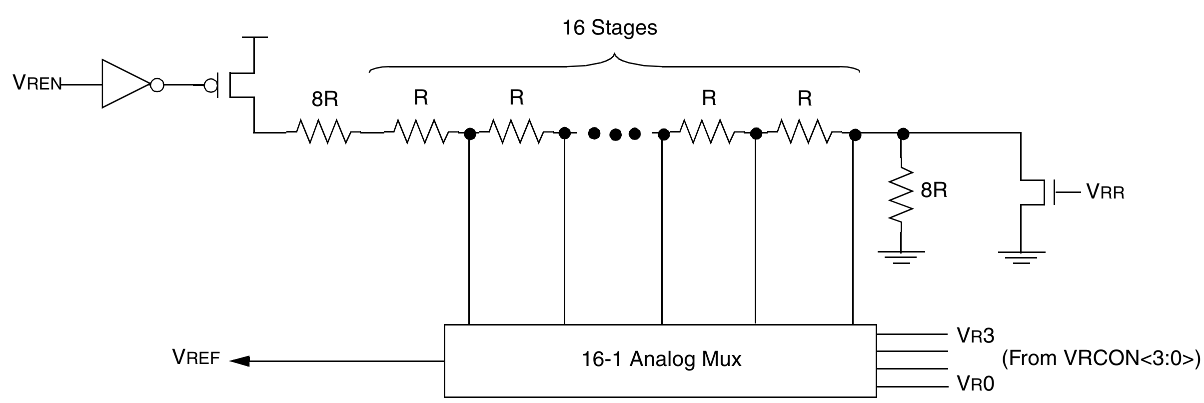
bit 6: **VROE:** V_{REF} Output Enable
1 = V_{REF} is output on RA2 pin
0 = V_{REF} is disconnected from RA2 pin

bit 5: **VRR:** V_{REF} Range selection
1 = Low Range
0 = High Range

bit 4: **Unimplemented:** Read as '0'

bit 3-0: **VR<3:0>**: V_{REF} value selection $0 \leq V_R[3:0] \leq 15$
when $V_{RR} = 1$: $V_{REF} = (V_R\langle 3:0\rangle/24) * V_{DD}$
when $V_{RR} = 0$: $V_{REF} = 1/4 * V_{DD} + (V_R\langle 3:0\rangle/32) * V_{DD}$

FIGURE 9-1: VOLTAGE REFERENCE BLOCK DIAGRAM



Note: R is defined in Table 13-2.

EXAMPLE 9-1: VOLTAGE REFERENCE CONFIGURATION

```
MOVLW    0x02        ; 4 Inputs Muxed
MOVWF    CMCON       ; to 2 comps.
BSF      STATUS,RP0  ; go to Bank 1
MOVLW    0x07        ; RA3-RA0 are
MOVWF    TRISA       ; outputs
MOVLW    0xA6        ; enable VREF
MOVWF    VRCON       ; low range
                     ; set VR<3:0>=6
BCF      STATUS,RP0  ; go to Bank 0
CALL     DELAY10     ; 10µs delay
```

9.2 Voltage Reference Accuracy/Error

The full range of VSS to VDD cannot be realized due to the construction of the module. The transistors on the top and bottom of the resistor ladder network (Figure 9-1) keep VREF from approaching VSS or VDD. The Voltage Reference is VDD derived and therefore, the VREF output changes with fluctuations in VDD. The absolute accuracy of the Voltage Reference can be found in Table 13-2.

9.3 Operation During Sleep

When the device wakes up from sleep through an interrupt or a Watchdog Timer time-out, the contents of the VRCON register are not affected. To minimize current consumption in SLEEP mode, the Voltage Reference should be disabled.

9.4 Effects of a Reset

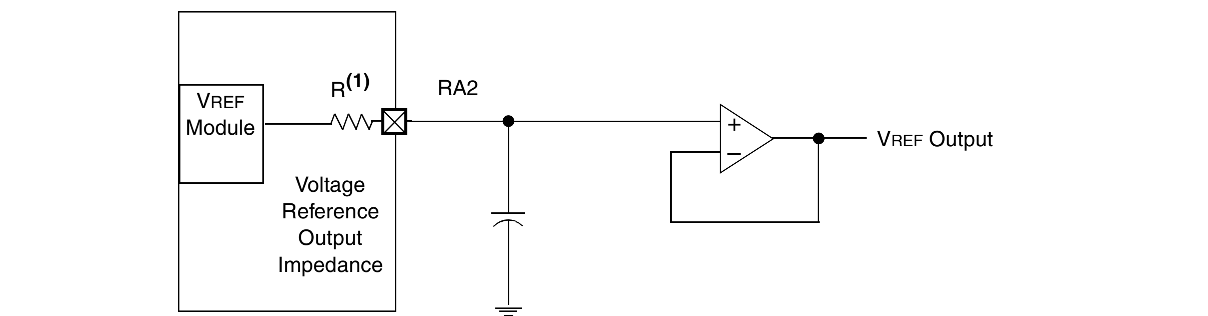
A device reset disables the Voltage Reference by clearing bit VREN (VRCON<7>). This reset also disconnects the reference from the RA2 pin by clearing bit VROE (VRCON<6>) and selects the high voltage range by clearing bit VRR (VRCON<5>). The VREF value select bits, VRCON<3:0>, are also cleared.

9.5 Connection Considerations

The Voltage Reference Module operates independently of the comparator module. The output of the reference generator may be connected to the RA2 pin if the TRISA<2> bit is set and the VROE bit, VRCON<6>, is set. Enabling the Voltage Reference output onto the RA2 pin with an input signal present will increase current consumption. Connecting RA2 as a digital output with VREF enabled will also increase current consumption.

The RA2 pin can be used as a simple D/A output with limited drive capability. Due to the limited drive capability, a buffer must be used in conjunction with the Voltage Reference output for external connections to VREF. Figure 9-2 shows an example buffering technique.

FIGURE 9-2: VOLTAGE REFERENCE OUTPUT BUFFER EXAMPLE



Note 1: R is dependent upon the Voltage Reference Configuration VRCON<3:0> and VRCON<5>.

TABLE 9-1: REGISTERS ASSOCIATED WITH VOLTAGE REFERENCE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value On POR / BOD	Value On All Other Resets
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	000- 0000	000- 0000
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	00-- 0000	00-- 0000
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: - = Unimplemented, read as "0"

10.1 Configuration Bits

The configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h – 3FFFh), which can be accessed only during programming.

REGISTER 10-1: CONFIGURATION WORD

CP1	CP0(2)	CP1	CP0(2)	CP1	CP0(2)	—	BODEN(1)	CP1	CP0(2)	$\overline{\text{PWRTE}}$(1)	WDTE	F0SC1	F0SC0
bit13													bit0

CONFIG REGISTER: Address 2007h

bit 13-8, 5-4: **CP1:CP0 Pairs:** Code protection bit pairs(2)

Code protection for 2K program memory
11 = Program memory code protection off
10 = 0400h-07FFh code protected
01 = 0200h-07FFh code protected
00 = 0000h-07FFh code protected

Code protection for 1K program memory
11 = Program memory code protection off
10 =Program memory code protection on
01 = 0200h-03FFh code protected
00 = 0000h-03FFh code protected

Code protection for 0.5K program memory
11 = Program memory code protection off
10 = Program memory code protection off
01 = Program memory code protection off
00 = 0000h-01FFh code protected

bit 7: **Unimplemented**: Read as '1'

bit 6: **BODEN**: Brown-out Reset Enable bit (1)
1 = BOD enabled
0 = BOD disabled

bit 3: **$\overline{\text{PWRTE}}$**: Power-up Timer Enable bit (1)
1 = PWRT disabled
0 = PWRT enabled

bit 2: **WDTE**: Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1-0: **FOSC1:FOSC0**: Oscillator Selection bits
11 = RC oscillator
10 = HS oscillator
01 = XT oscillator
00 = LP oscillator

Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT), regardless of the value of bit $\overline{\text{PWRTE}}$. Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled.

2: All of the CP<1:0> pairs have to be given the same value to enable the code protection scheme listed.

10.8 Power-Down Mode (SLEEP)

The Power-down mode is entered by executing a `SLEEP` instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the $\overline{\text{PD}}$ bit in the STATUS register is cleared, the $\overline{\text{TO}}$ bit is set and the oscillator driver is turned off. The I/O ports maintain the status they had before `SLEEP` was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, all I/O pins should be either at VDD or VSS, with no external circuitry drawing current from the I/O pin, and the comparators and VREF should be disabled. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at VDD or VSS for lowest current consumption. The contribution from on chip pull-ups on PORTB should be considered.

The $\overline{\text{MCLR}}$ pin must be at a logic high level (VIHMC).

Note:	It should be noted that a RESET generated by a WDT time-out does not drive $\overline{\text{MCLR}}$ pin low.

10.8.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External reset input on $\overline{\text{MCLR}}$ pin
2. Watchdog Timer Wake-up (if WDT was enabled)
3. Interrupt from RB0/INT pin, RB Port change, or the Peripheral Interrupt (Comparator).

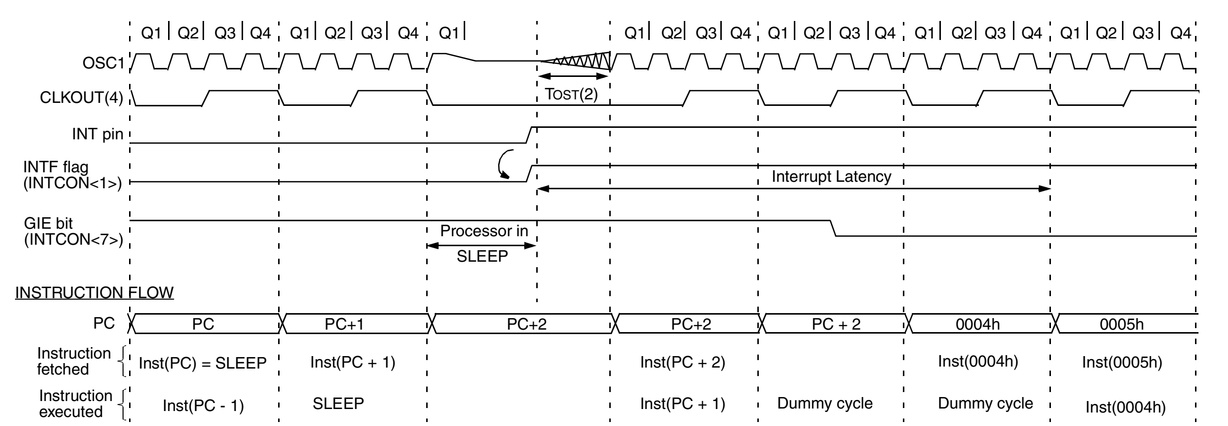
The first event will cause a device reset. The two latter events are considered a continuation of program execution. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits in the STATUS register can be used to determine the cause of device reset. $\overline{\text{PD}}$ bit, which is set on power-up is cleared when SLEEP is invoked. $\overline{\text{TO}}$ bit is cleared if WDT wake-up occurred.

When the `SLEEP` instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the `SLEEP` instruction. If the GIE bit is set (enabled), the device executes the instruction after the `SLEEP` instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following `SLEEP` is not desirable, the user should have an `NOP` after the `SLEEP` instruction.

Note:	If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from sleep. The sleep instruction is completely executed.

The WDT is cleared when the device wakes-up from sleep, regardless of the source of wake-up.

FIGURE 10-19: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT, HS or LP oscillator mode assumed.
2: TOST = 1024TOSC (drawing not to scale) This delay does not occur for RC osc mode.
3: GIE = '1' assumed. In this case after wake- up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.
4: CLKOUT is not available in these osc modes, but shown here for timing reference.

SWAPF **Swap Nibbles in f**

Syntax:	[*label*] SWAPF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f<3:0>) → (dest<7:4>), (f<7:4>) → (dest<3:0>)
Status Affected:	None
Encoding:	`00` | `1110` | `dfff` | `ffff`
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in W register. If 'd' is 1, the result is placed in register 'f'.
Words:	1
Cycles:	1
Example	`SWAPF REG, 0`

Before Instruction

REG1 = 0xA5

After Instruction

REG1 = 0xA5
W = 0x5A

TRIS **Load TRIS Register**

Syntax:	[*label*] TRIS f
Operands:	$5 \le f \le 7$
Operation:	(W) → TRIS register f;
Status Affected:	None
Encoding:	`00` | `0000` | `0110` | `0fff`
Description:	The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.
Words:	1
Cycles:	1
Example	

To maintain upward compatibility with future PIC® MCU products, do not use this instruction.

XORLW **Exclusive OR Literal with W**

Syntax:	[*label*] XORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .XOR. k → (W)
Status Affected:	Z
Encoding:	`11` | `1010` | `kkkk` | `kkkk`
Description:	The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.
Words:	1
Cycles:	1
Example:	`XORLW 0xAF`

Before Instruction

W = 0xB5

After Instruction

W = 0x1A

XORWF **Exclusive OR W with f**

Syntax:	[*label*] XORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) → (dest)
Status Affected:	Z
Encoding:	`00` | `0110` | `dfff` | `ffff`
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example	`XORWF REG 1`

Before Instruction

REG = 0xAF
W = 0xB5

After Instruction

REG = 0x1A
W = 0xB5

NOTES:

13.2 DC CHARACTERISTICS: PIC16LCE62X-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature –40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	2.5	–	5.5	V	See Figure 13-1 through Figure 13-3
D002	VDR	RAM Data Retention Voltage (Note 1)	–	1.5*	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	–	VSS	–	V	See section on power-on reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	.05*	–	–	V/ms	See section on power-on reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current (Note 2)	– – –	1.2 – 35	2.0 1.1 70	mA mA µA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT osc mode, (Note 4)* FOSC = 4 MHz, VDD = 2.5V, WDT disabled, XT osc mode, (Note 4) FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP osc mode
D020	IPD	Power Down Current (Note 3)	– – – –	– – – –	2.0 2.2 9.0 15	µA µA µA µA	VDD = 2.5V VDD = 3.0V* VDD = 5.5V VDD = 5.5V Extended
D022	ΔIWDT	WDT Current (Note 5)	–	6.0	10 12	µA µA	VDD=4.0V (125°C)
D022A	ΔIBOR	Brown-out Reset Current (Note 5)	–	75	125	µA	$\overline{\text{BOD}}$ enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator (Note 5)	–	30	60	µA	VDD = 4.0V
D023A	ΔIVREF	VREF Current (Note 5)	–	80	135	µA	VDD = 4.0V
	ΔIEE Write ΔIEE Read ΔIEE ΔIEE	Operating Current Operating Current Standby Current Standby Current	– – – –		3 1 30 100	mA mA µA µA	VCC = 5.5V, SCL = 400 kHz VCC = 3.0V, EE VDD = VCC VCC = 3.0V, EE VDD = VCC
1A	FOSC	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0	— — — —	200 4 4 20	kHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

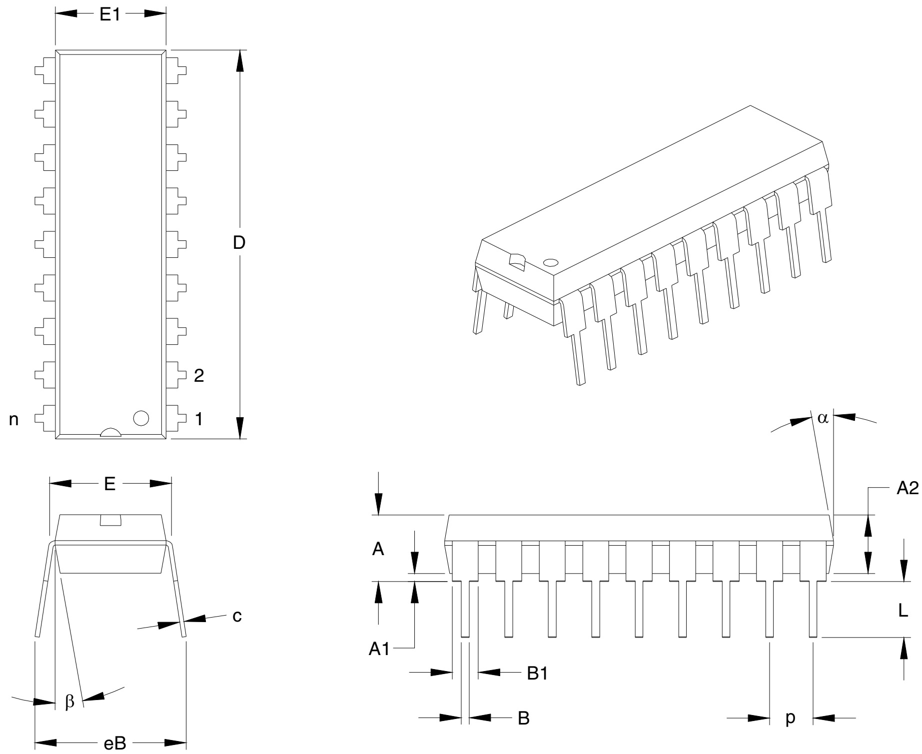
4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

*Controlling Parameter

Notes:

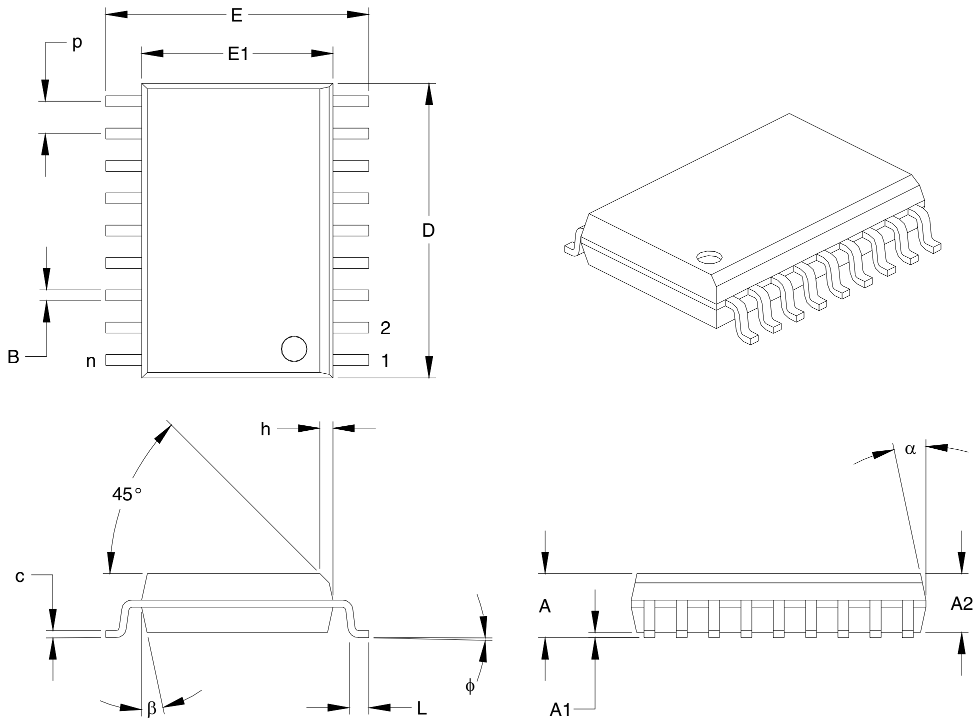
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-007

18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.

JEDEC Equivalent: MS-013

Drawing No. C04-051

APPENDIX A: CODE FOR ACCESSING EEPROM DATA MEMORY

Please check our web site at www.microchip.com for code availability.

APPENDIX B:REVISION HISTORY

Revision D (January 2013)

Added a note to each package outline drawing.